

## APPROVAL SHEET

# WW25X, WW18X, WW12X, WW08X, WW06X

±1%, ±5%

Thick Film Current Sensing Chip Resistors Size 2512, 1218, 1206, 0805, 0603 (Automotive)



#### **FEATURE**

- 1. High power rating and compact size
- 2. Automotive AEC Q-200 Compliant
- 3. 100% CCD Visual inspection
- 4. RoHS compliant and Lead free products

#### **APPLICATION**

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

#### **DESCRIPTION**

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to nominated value within tolerance which controlled by laser trimming of this resistive layer.

The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a lead free tin alloy.

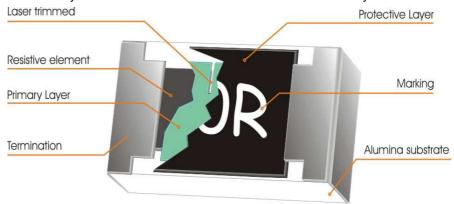


Fig 1. Construction of 2512, 1206, 0805, 0603 Chip-R

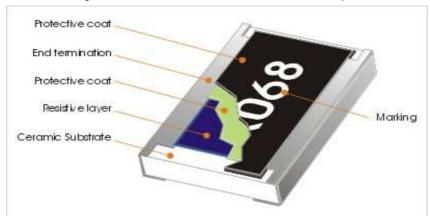


Fig 2. Construction of a 1218 Chip-R

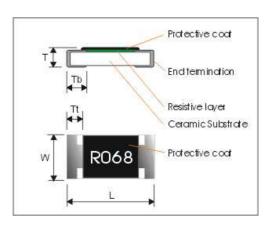


#### **QUICK REFERENCE DATA**

Item	General Specification				
Series No.	WW25X	WW18X	WW12X	WW08X	WW06X
Size code	2512 ( 6432 )	1218 (3248)	1206 (3216)	0805 (2012)	0603 (1608)
Resistance Tolerance	±5		±5%, ±1%		
			(E24+E96)		
Resistance Range	0.02Ω ~ 0.976Ω	0.02Ω ~ 0.976Ω	$0.02\Omega \sim 0.976\Omega$	0.02Ω ~ 0.976Ω	0.1Ω ~ 0.976Ω
TCR (ppm/°C)					
$0.02\Omega \le Rn < 0.05\Omega$	≤ 2100 ppm/°C	≤ 1500 ppm/°C	≤ 2100 ppm/°C	≤ 1500 ppm/°C	
$0.05\Omega \le Rn < 0.10\Omega$	≤ 1000 ppm/°C	≤ 1000 ppm/°C	≤ 1000 ppm/°C	≤ 1000 ppm/°C	
$0.10\Omega \le Rn < 0.50\Omega$	≤ 500 ppm/°C	≤ 500 ppm/°C	≤ 500 ppm/°C	≤ 500 ppm/°C	≤ 500 ppm/°C
$0.50\Omega \le Rn < 1\Omega$	≤ 400 ppm/°C	≤ 300 ppm/°C	≤ 400 ppm/°C	≤ 300 ppm/°C	≤ 300 ppm/°C
Max. dissipation at T <sub>amb</sub> =70°C	1 W	1 W	1/4 W	1/8 W	1/10W
Max. Operation Current (DC or RMS)	7.07 ~ 1.01A	7.07 ~ 1.01A	3.53 ~ 0.50A	2.50 ~ 0.35A	1.0 ~ 0.3A
Max. Overload Current (DC or RMS)	14.14 ~ 2.02A	14.14 ~ 2.02A	7.06 ~ 1.0A	5.00 ~ 0.70A	2.0 ~ 0.6A
Operation Temperature	-55/+155'C	-55/+155'C	-55/+155'C	-55/+155'C	-55/+155'C

## **MECHANICAL DATA (unit: mm)**

Dimension	WW25	WW18	WW12	WW08	WW06
L	6.40±0.20	3.05±0.15	3.10 ± 0.10	2.00 ± 0.10	1.60 ± 0.10
W	3.20±0.20	4.60±0.20	1.60 ± 0.10	1.25 ± 0.10	0.80 ± 0.10
Т	0.60±0.10	0.55±0.10	0.60 ± 0.15	0.50 ± 0.15	0.45 ± 0.15
Tt	0.65±0.25	0.45±0.25	0.50 ± 0.20	0.40 ± 0.20	0.30 ± 0.10
Tb	0.90±0.25	0.50±0.25	0.45 ± 0.20	0.40 ± 0.20	0.30 ± 0.20





#### **MARKING**

For 0805 and above sizes, each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

Example:

 $R010 = 0.01\Omega$  $R510 = 0.51\Omega$ 

For 0603 size, each resistor is marked with a three-digit code on the protective coating to designate the nominal resistance value.

Example:

 $R10 = 0.10\Omega$  $R51 = 0.51\Omega$ 

#### **FUNCTIONAL DESCRIPTION**

#### **Product characterization**

Standard values of nominal resistance are taken from the E96 & E24 series for resistors with a tolerance of  $\pm 5\%$  &  $\pm 1\%$ . The values of the E24/E96 series are in accordance with "IEC publication 60063".

#### **Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.3

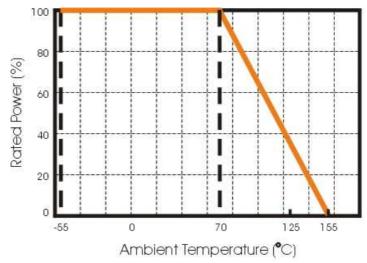


Fig 3. Max. dissipation in percentage of rated power as a function of the ambient temperature

#### **MOUNTING**

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



#### **SOLDERING CONDITION**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 4.

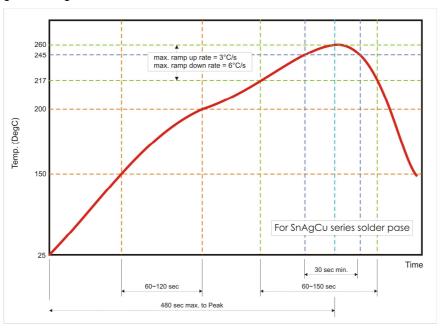


Fig 4. Infrared soldering profile for Chip Resistors

#### **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with .

WW25	Х	R020	J	Т	L	J			
Size code	Type code	Resistance code	Tolerance	Packaging	Termination	Special code			
WW25 : 2512	X : Normal	E96 +E24:	J : ±5%	code	code	J = Automotive grade			
WW18 : 1218		R is first digit followed by	F:±1%	T : Reeled	L = Sn base (lead free)	AEC Q-200 compliant,			
WW12 : 1206		3 significant digits.	5					(100000000)	100% CCD visual
WW08 : 0805		$0.020\Omega = R020$				inspection			
WW06 : 0603		$0.510\Omega = R510$							
		$0.025\Omega = R025$							



### **TEST AND REQUIREMENTS (AEC Q-200)**

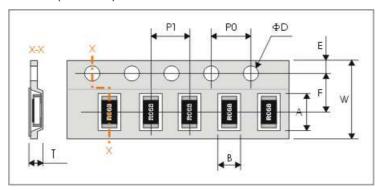
TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
IESI	PROCEDURE/TEST METHOD	Resistor		
Electrical Characteristics	- DC resistance values measurement	Within the specified tolerance		
	- Temperature Coefficient of Resistance (T.C.R)	Refer to "QUICK REFERENCE		
JISC5201-1: 1998	Natural resistance change per change in degree	DATA"		
Clause 4.8	centigrade.			
	$\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}  t_1 : 20\text{C} + 5\text{C} - 1\text{C}$			
	R <sub>1</sub> : Resistance at reference temperature			
	R <sub>2</sub> : Resistance at test temperature			
Resistance to soldering	Un-mounted chips completely immersed for	$\Delta$ R/R max. ±(0.5%+0.005Ω)		
heat(R.S.H)	10±1second in a SAC solder bath at 270°C±5°C	no visible damage		
MIL-STD-202 method 210				
Solderability J-STD-002	<ul> <li>a) Bake the sample for 155°C dwell time 4hrs/ solder dipping 235°C/ 5sec.</li> <li>b) Steam the sample dwell time 8 hour/ solder dipping 215°C/ 5sec.</li> <li>c) Steam the sample dwell time 8 hour/ solder dipping 260°C/ 7sec.</li> </ul>	95% coverage min., good tinning and no visible damage		
Temperature cycling	1000 cycles, $-55^{\circ}$ C ~ $+155^{\circ}$ C, dwell time 30min	$\Delta$ R/R max. $\pm$ (0.5%+0.005 $\Omega$ )		
JESD22	maximum.	No visible damage		
Method JA-104				
Moisture Resistance MIL- STD-202	65±2°C, 80~100% RH, 10 cycles, 24 hours/ cycle	$\Delta$ R/R max. $\pm$ (1.0%+0.005 $\Omega$ ) No visible damage		
method 106				
Bias Humidity	1000+48/-0 hours; 85°C, 85% RH, 10% of operation	$\Delta$ R/R max. $\pm$ (1.0%+0.005 $\Omega$ )		
MIL-STD-202	power	No visible damage		
method 103				
Operational Life	1000+48/-0 hours; 35% of operation power, 125±2°C	$\Delta$ R/R max. ±(1.0%+0.005Ω)		
MIL-STD-202 method 108		No visible damage		
High Temperature	1000+48/-0 hours; without load in a temperature	$\Delta$ R/R max. $\pm$ (1%+0.005 $\Omega$ )		
Exposure	chamber controlled 155±3°C	No visible damage		
MIL-STD-202				
Method 108				
Board Flex	Resistors mounted on a 90mm glass epoxy resin	$\Delta$ R/R max. $\pm$ (1.0%+0.005 $\Omega$ )		
AEC-Q200-005	PCB(FR4),bending once 2mm for 60sec.	No visible damage		
Terminal strength	Pressurizing force: 1.8Kg, Test time: 60±1sec.	No remarkable damage or		
AEC-Q200-006		removal of the terminations		
Thermal shock	Test −55 to 155°C/ dwell time 15min/ Max transfer time	$\Delta$ R/R max. $\pm$ (0.5%+0.005 $\Omega$ )		
MIL-STD-202	20sec 300cycles	No visible damage		
method 107				
ESD	Test contact 25KV (air)	$\Delta$ R/R max. $\pm$ (1.0%+0.005 $\Omega$ )		
AEC-Q200-002		No visible damage		



Mechanical Shock MIL-STD-202 method 213	Test ½ Sine Pulse, Peak value: 100g, normal duration: 6ms, Velocity change:12.3ft/sec. Three shocks in each direction, total 18 shocks.	Within product specification tolerance and no visible damage.
Vibration MIL-STD-202 method 204	Test 5g's for 20 min., 12 cycles each of 3 orientations.	$\triangle$ R/R max. $\pm$ (0.5%+0.005 $\Omega$ ) and no visible damage.
Resistance to Solvents : MIL-STD-202 Method 215	Solvent is Isopropyl alcohol, immersion 3mins at 25°C and brush 10 strokes with a toothbrush with a handle made of a non-reactive material (wet bristle), immersion and brush 3 times and then air blow dry.	No superficial defect on marking, encapsulation, coating, appearance. Electrical characteristics within products specification and tolerance. Inspect at 3X max. for marking, inspect at 10X for part damage.
External Visual MIL-STD-883 method 2009	Electrical test not required. Inspect device construction, marking and workmanship	No visual damage and refer WTC marking code.
Physical Dimension JESD22 method JB-100	Verify physical dimensions(L, W, T, Tb, Tt)	Within the specified tolerance for WTC.

#### **PACKAGING**

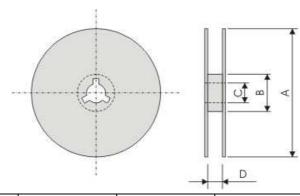
#### Plastic Tape specifications (unit: mm)



Туре	Α	В	W	F	E
WW25	6.90±0.20	3.60±0.20	12.00±0.30	5.50±0.1	1.75±0.10
WW18	4.90±0.20	3.55±0.30	12.00±0.30	5.50±0.1	1.75±0.10
WW12	3.60±0.20	2.00±0.20	8.00±0.30	3.50±0.2	1.75±0.10
WW08	2.40±0.20	1.65±0.20	8.00±0.30	3.50±0.2	1.75±0.10
WW06	1.90±0.20	1.10±0.20	8.00±0.30	3.50±0.2	1.75±0.10

Туре	P1	P0	ΦD	Т
WW25	4.00±0.10	4.00±0.10		Max. 1.2
WW18	8.00±0.10	4.00±0.10		1.30±0.20
WW12	4.00±0.10	4.00±0.10	$\Phi$ 1.50 $^{+0.1}_{-0.0}$	Max. 1.0
WW08	4.00±0.10	4.00±0.10		Max. 1.0
WW06	4.00±0.10	4.00±0.10		0.65±0.05

#### **Reel dimensions**



(unit : mm)	Α	В	С	D
WW25/ WW18	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	14.0±0.2
WW12/ 08/ 06	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	9.0±0.5

#### **Taping Quantity**

- WW25 by plastic tape taping 4,000 pcs per reel.
- WW18 by plastic tape taping 3,000 pcs per reel
- WW12, WW08, WW06 by paper tape taping 5,000 pcs per reel